5632DA

Semi-automatic Wedge-Wedge-Bonder

The semi-automatic Wedge-Wedge Bonder 5632 fills the gap between the manual Wedge-Bonders series 53xx and 54xx to the automatic-Bonder. The 5632 Deep-Access Bonder can be used also as Ribbon-Bonder.

He is on basis 5600-series fully PC controlled and allows any number of bonds to be programmed.

Pre-programmed adjust points are targeted through the camera's cross hair targeting system and the programmed bonds are executed automatically.

Two operating modes are available: Single bond for repair of various bond samples and making single bonds (manual-automatic) and multi wire for teaching and bonding chips or various bond samples (semi and fully automatic).

The 5632 can also be used as Gold Wire, Ball or Alu Heavy Wire Bonder as well as pull-/shear tester by simply replacing the bond head and loading the appropriate software.

change over time: approx. 5 minutes.

Ask us for more information !

Specifications

Mechanics

X, Y table	Working area 100 x 115 mm
	Resolution 0.25 µm, repeatability < 2 µm
Z-axis	60 mm
Speed	*up tp* ≤20 wires / min.
Bond head	Wedge-Wedge Thin-Wire (Au/Al) or Ribbon
	Axis of rotation ± 360°
Ultrasonic system	65KHz / 100kHz optional 140KHz
Wire size	17,5mm up to 75µm
Ribbon size	30 µm x 12,5 µm – 250 µm x 25 µm

Control

Heating-controller	Integrated in machine 0 - 250 °C optional
Computer	Dual Core PC, 1,6 GHz Processor, 4 GB RAM, Ethernet, USB 4x + 4x frontside
Monitor	TFT flat screen
Operation system	Windows 7
Printer	All Windows-compatible printers can be installed All bonding parameters can be printed
Work holder	ø 80mm or optional 4x4"
Heated work holder	ø 80mm and optional 4x4" (mech. / vacuum) (Attention: 4x4" up to 200°C; 80 mm up to 250°C)

Other features

Programming:	Automatic bonding of hybrids or COB with programmable X/Y table

Rev. 03
07_2007

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Work holders

For components up to 4 x 4"

Vacuum and mechanical clamping

Heated workholders optional

For components up to 4 x 4"
For components up to ø 80 mm

Vacuum and mechanical clamping
Heated

Vacuum and mechanical clamping
heated

More Work holders available on request.

Head Parking System	For storing of temporary not required bondhead (5610 / 5630 / 5632 / 5650) or pull- and shear-heads. Can be mounted on the left or right side of the machine
General	
Camera	With cross hair targeting for positioning of bonds / chips
Microscope	Stereoskop Standard 40x, other Microscopes optional
Lighting	20 W halogen spot light, optional LED direct light Incident light optional, incident light, ringlight and spotlight programmable
Dimensions	Height 70 cm, width 70 cm, depth 65 cm; approx. 70 kg
Supplies	100...240 VAC, single-phase, 50/60 Hz, max.500VA
Connections	Air 6 bar, vacuum 0,7 bar ø 6 mm

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